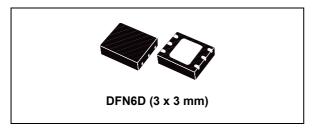


1.5 A, 1.5 MHz adjustable, step-down switching regulator

Datasheet - production data



Features

- Step-down current mode PWM (1.5 MHz) DC-DC converter
- 2% DC output voltage tolerance
- Internal soft-start for STARTUP current limitation and power on delay of 50 - 100 μs
- Typical efficiency: > 70% over all operating conditions
- 1.5 A output current capability
- Not switching quiescent current: max 2.5 mA over temperature range
- Switch V_{DS}: max. 350 mV at I_{SW} = 750 mA
- Uses tiny capacitors and inductors
- Available in DFN6D 3 x 3 mm package with exposed pad

Description

The ST1S03 is a step-down DC-DC converter optimized for powering a low voltage digital core in HDD applications and, generally, to replace the high current linear solution when the power dissipation may cause a high heating of the application environment. It provides up to 1.5 A over an input voltage range of 3 V to 16 V. A high switching frequency (1.5 MHz) allows the use of tiny surface-mount components: as well as the resistor divider to set the output voltage value, only an inductor, a Schottky diode and two capacitors are required. Besides, a low output ripple is guaranteed by the current mode PWM topology and by the use of low ESR SMD ceramic capacitors. The device is thermal protected and current limited to prevent damages due to an accidental short-circuit. The ST1S03 device is available in a DFN6D package.

Table 1. Device summary

Order code	Package	Packaging	
ST1S03PUR	DFN6D (3 x 3 mm)	Tape and reel	

ST1S03

Contents

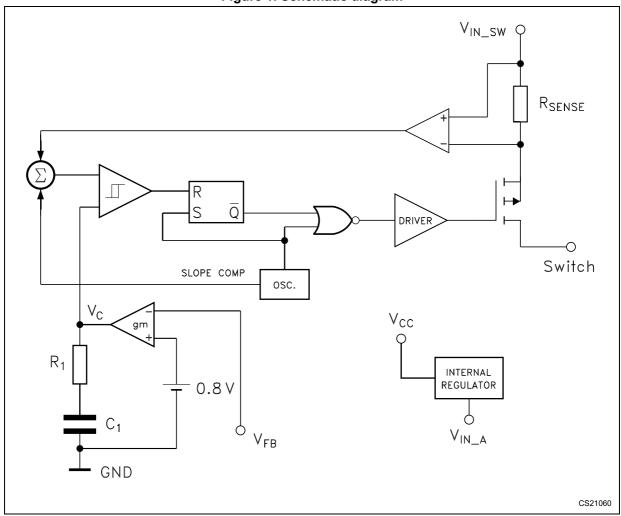
1	Diagram	. 3
2	Pin configuration	. 4
3	Maximum ratings	. 5
4	Electrical characteristics	. 6
5	Application notes	. 7
6	Typical application	. 8
7	Typical performance characteristics	. 9
8	Package information	12
9	Revision history	15



ST1S03 Diagram

1 Diagram

Figure 1. Schematic diagram



Pin configuration ST1S03

2 Pin configuration

Figure 2. Pin connections (top view)

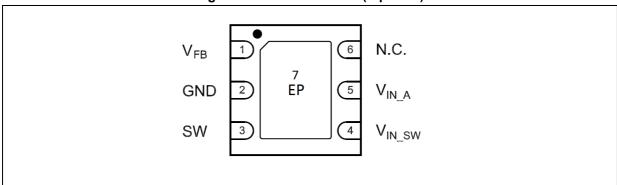


Table 2. Pin description

Pin no.	Symbol	Name and function	
1	V_{FB}	Voltage of feedback	
2	GND	System ground	
3	SW	Output of the internal power switch	
4	V _{IN_SW}	Power supply for the MOSFET switch	
5	V _{IN_A}	Power supply for the analog circuit	
6	N.C.	Not connected	
7	EP	Exposed pad should be connected to GND	

ST1S03 Maximum ratings

3 Maximum ratings

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{IN_SW}	Positive power supply voltage	-0.3 to 16	V
V _{IN_A}	Positive power supply voltage	-0.3 to 16	V
SWITCH voltage	Max voltage of output pin	-0.3 to 16	V
V _{FB} Feedback voltage		2.5	V
I _{VFB} Common mode input voltage		±1	mA
T _J	Max junction temperature	150	°C
T _{STG} Storage temperature range		-25 to 150	°C
T _{LEAD} Lead temperature (soldering) 10 s		300	°C

Note: Absolute maximum ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied.

Table 4. Thermal data

Symbol	Parameter	Value	Unit
R _{thJC} Thermal resistance junction case		10	°C/W
R _{thJA} Thermal resistance junction ambient		55	°C/W

Electrical characteristics ST1S03

4 Electrical characteristics

Table 5. Electrical characteristics (V_{IN_SW} = V_{IN_A} = 5 V, C_I = 4.7 μ F, C_O = 22 μ F, L1 = 3.3 μ H, T_J = 0 to 125 °C, unless otherwise specified. Typical values are referred to 25 °C)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
FB	Feedback voltage	I _O = 100 mA	784	800	816	mV
I _{FB}	V _{FB} pin bias current				600	nA
IQ	Quiescent current	No switching			2.5	mA
Io	Output current	V _{IN} = 3 V to 16 V	1.5			Α
I _{MIN}	Minimum output current		1			mA
%V _O /ΔV _{IN}	Reference line regulation	V _{IN} = 3 V to 16 V		0.032	0.06	% V _O /ΔV _{IN}
%V _O /∆I _O	Reference load regulation	I _O = 10 mA to 1.2 A		0.0014	0.003	% V _O /mA
PWM f _S	PWM switching frequency ⁽¹⁾	V _{FB} = 0.8 V, T _A =25 °C	1.2	1.5	1.8	MHz
D _{MAX}	Maximum duty cycle			87		%
I _{SWL}	Switching current limitation		1.65			Α
V _{DS}	Switch V _{DS}	I _{SW} = 750 mA		200	350	mV
Е	Efficiency	I _O = 10 mA to 1.2 A	70			%
T _{SHDN}	Thermal shutdown ⁽¹⁾		130	150		°C
T _{HYS}	Thermal shutdown hysteresis ⁽¹⁾			15		°C
$\Delta V_{O}/\Delta I_{O}$	Load transient response ⁽¹⁾	I_{O} = 100 mA to 700 mA t_{R} = t_{F} \geq 100 ns, T_{A} = 25 °C	-5	_	+5	% V _O
$\Delta V_O / \Delta I_O at$ $I_O = short$	Short-circuit removal response ⁽¹⁾	I_O = 10 mA to short, T_A = 25 °C		_	+5	% V _O

^{1.} Guaranteed by design, but not tested in production.

47/

ST1S03 Application notes

5 Application notes

The ST1S03 is an adjustable current mode PWM step-down DC-DC converter with an internal 1.5 A power switch, housed in a 6-lead DFN 3 x 3 mm package.

It's a complete 1.5 A switching regulator with its internal compensation eliminating an additional component.

The constant frequency, current mode, PWM architecture and stable operation with ceramic capacitors results in a low, predictable output ripple. However, in order to keep the output regulated, the devices goes in pulse skipping mode when a very light load is required.

To clamp the error amplifier reference voltage, a soft-start control block generating a voltage ramp has been implemented. Besides an on-chip power on reset of $50 = 100 \,\mu s$ ensures the proper operation when switching on the power supply. Other circuits fitted to the device protection are the thermal shutdown blocks which turn off the regulator when the junction temperature exceeds 150 °C typically and the cycle-by-cycle current limiting that provides protection against shorted outputs.

Being the ST1S03 an adjustable regulator, the output voltage is determined by an external resistor divider. The desired value is given by the following equation:

$$V_0 = V_{FB} [1 + R1 / R2]$$

To make the device working, only other four external components are required: a Schottky diode, an inductor and two capacitors. The chosen inductor must be able to not saturate at the peak current level. Besides, its value can be selected keeping in account that a large inductor value increases the efficiency at a low output current and reduces an output voltage ripple, while a smaller inductor can be chosen when it is important to reduce the package size and the total cost of the application. Finally, the ST1S03 device has been designed to work properly with the X5R or X7R SMD ceramic capacitors both at the input and at the output. This kind of capacitors, thanks to their very low series resistance (ESR), minimize the output voltage ripple. Other low ESR capacitors can be used according to the need of the application without invalidating the right functioning of the device. Due to the high switching frequency and peak current, it is important to optimize the application environment reducing the length of the PCB traces and placing all the external components near the device.



DocID10992 Rev 7 7/16

Typical application ST1S03

6 Typical application

V_{IN} \bigcirc \bigvee V_{IN_A} \bigvee ST1S03 \bigvee V_{IN_SW} \bigvee SW \bigvee

Figure 3. Application circuits



CS21050

7 Typical performance characteristics

(L1 = 3.3 μ H, C_I = 4.7 μ F, C_O = 22 μ F, unless otherwise specified).

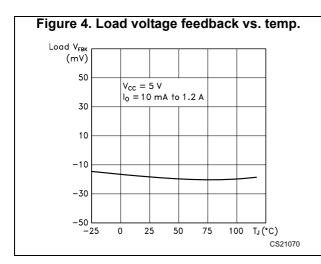


Figure 5. Voltage feedback vs. temperature

V_{FBK}
(mV)

850

V_{CC} = 5 V

I₀ = 10 mA

750

700

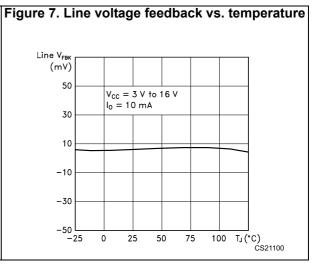
-25 0 25 50 75 100 T_J(*C)

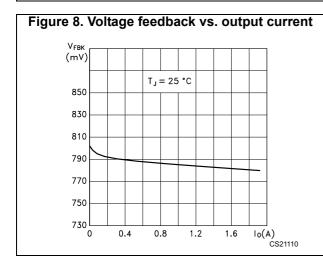
CS21080

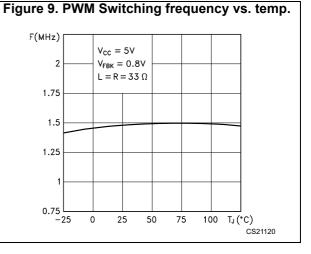
Figure 6. Line output voltage regulation vs. temperature

Line V_o
(mV)
50
V_{cc} = 3 V to 16 V
I_o = 10 mA

10
-10
-30
-50
-25
0
25
50
75
100
T_J(*C)
CS21090







57/

DocID10992 Rev 7

9/16

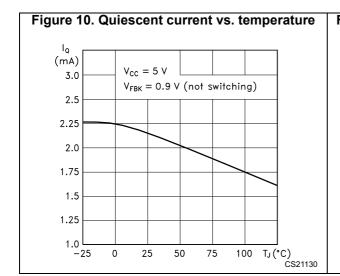


Figure 11. Quiescent current vs. input voltage

(mA)
3.0
V_{FBK} = 0.9 V (not switching)
2.5
2.25
2.0
1.75
1.5
1.25
1.0
0 2 4 6 8 10 12 14 V_{CC}(V)
CS21140

Figure 12. Minimum operating voltage vs. output voltage

V_{cc}(V)

3.5

2

1.5

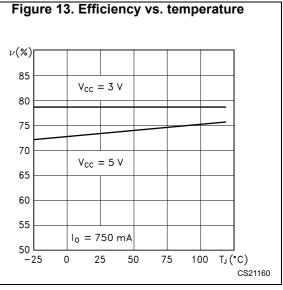
2

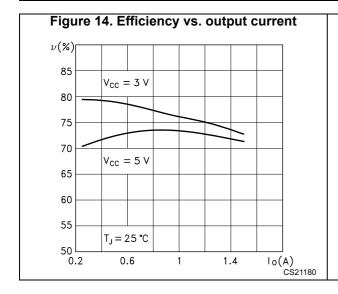
1.5

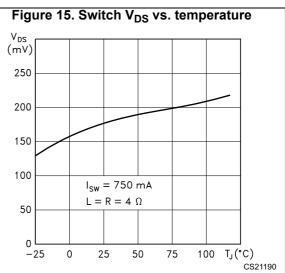
2

1.5

CS21150

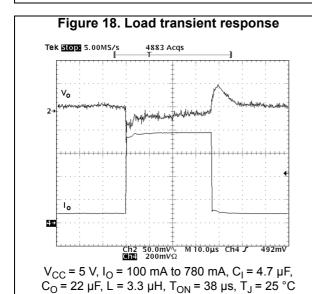


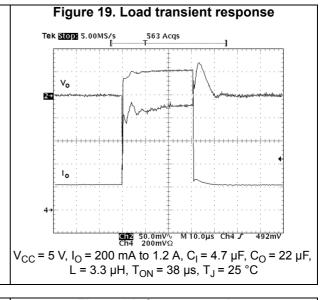


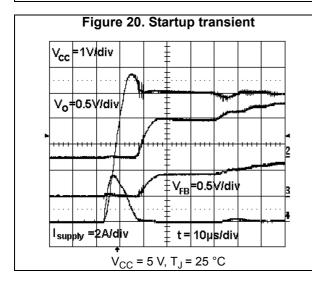


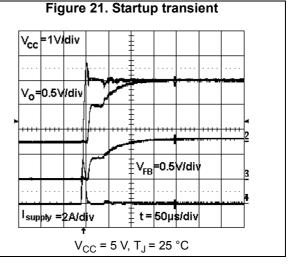
10/16 DocID10992 Rev 7

Figure 16. Switch RDS-ON vs. temperature R_{DS}-ON (Ω) $V_{CC} = 5 V$ $I_{sw} = 750 \text{ mA}$ 0.5 $L = R = 4 \Omega$ 0.4 0.3 0.2 0.1 100 T_J(°C) CS21200 -2525 50 75









DocID10992 Rev 7

11/16

Package information ST1S03

8 Package information

12/16

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

DocID10992 Rev 7

ST1S03 Package information

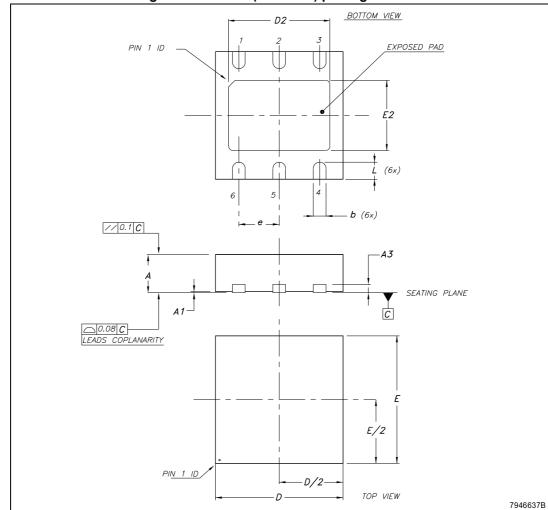


Figure 22. DFN6D (3 x 3 mm) package outline

Table 6. DFN6D (3 x 3 mm) package mechanical data

Symbol	Dimensions (mm)			Dimensions (inch)		
Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.
А	0.80		1.00	0.031		0.039
A1	0	0.02	0.05	0	0.001	0.002
A3		0.20			0.008	
b	0.23		0.45	0.009		0.018
D	2.90	3.00	3.10	0.114	0.118	0.122
D2	2.23		2.50	0.088		0.098
Е	2.90	3.00	3.10	0.114	0.118	0.122
E2	1.50		1.75	0.059		0.069
е		0.95			0.037	
L	0.30	0.40	0.50	0.012	0.016	0.020



DocID10992 Rev 7 13/16

Package information ST1S03

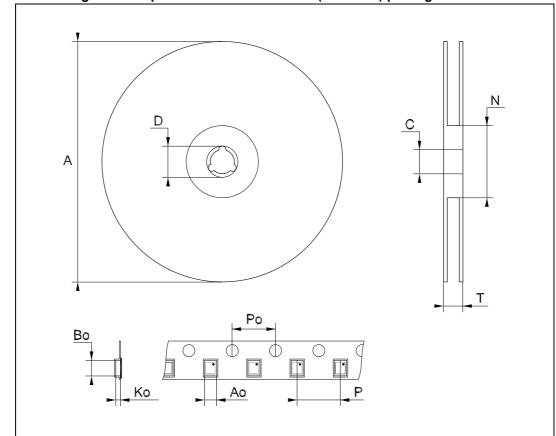


Figure 23. Tape and reel QFNxx/DFNxx (3 x 3 mm) package outline⁽¹⁾

1. Drawing is not in scale.

Table 7. Tape and reel QFNxx/DFNxx (3 x 3 mm) package mechanical data

Comple of	Dimensions (mm)			Dimensions (inch)		
Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.
А			330			12.992
С	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
Т			18.4			0.724
Ao		3.3			0.130	
Во		3.3			0.130	
Ko		1.1			0.043	
Ро		4			0.157	
Р		8			0.315	

ST1S03 Revision history

9 Revision history

Table 8. Document revision history

Date	Revision	Changes	
11-Nov-2004	1	First Release.	
08-Feb-2005	2	Maturity Change.	
03-Mar-2005	3	Mistake on Figure 1, T _J is changed 125 ==> 150°C on Table 3.	
13-Jul-2005	4	Add new package SO-8 exposed pad.	
29-Mar-2007	5	Package SO-8 removed.	
07-Mar-2008 6 Removed: package mechanical data DFN6.		Removed: package mechanical data DFN6.	
14-Nov-2014 7		Updated <i>Table 1: Device summary on page 1</i> (updated Packaging). Updated <i>Figure 2: Pin connections (top view) on page 4</i> (replaced by new figure). Updated <i>Table 2: Pin description on page 4</i> (added row 7). Updated <i>Section 8: Package information on page 12</i> (updated and added titles, updated ECOPACK text, reversed order of <i>Figure 22</i> and <i>Table 6</i> , <i>Figure 23</i> and <i>Table 7</i> , updated headings of <i>Table 6</i> and <i>Table 7</i>). Minor modifications throughout document.	



IMPORTANT NOTICE - PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2014 STMicroelectronics – All rights reserved

57

16/16 DocID10992 Rev 7

单击下面可查看定价,库存,交付和生命周期等信息

>>STMicro(意法半导体)